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(54) Title: ELECTROSTATIC CHUCK WITH PHOTO-PATTERNABLE SOFT PROTRUSION CONTACT SURFACE

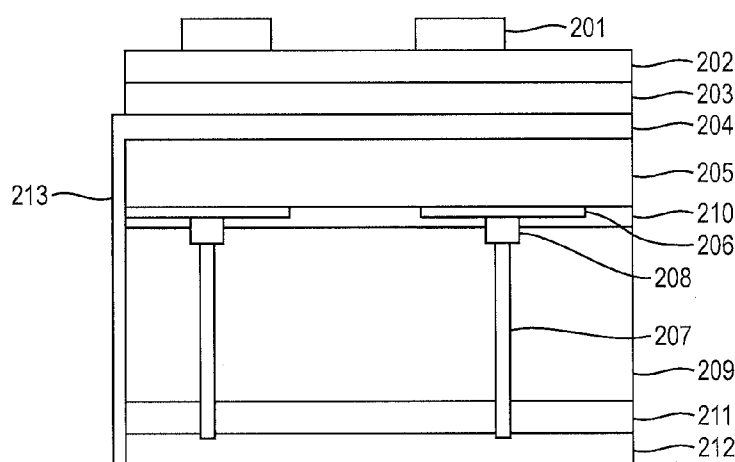


FIG. 2

(57) Abstract: In accordance with an embodiment of the invention, there is provided a soft protrusion structure for an electrostatic chuck, which offers a non-abrasive contact surface for wafers, workpieces or other substrates, while also having improved manufacturability and compatibility with grounded surface platen designs. The soft protrusion structure comprises a photo-patternable polymer.



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